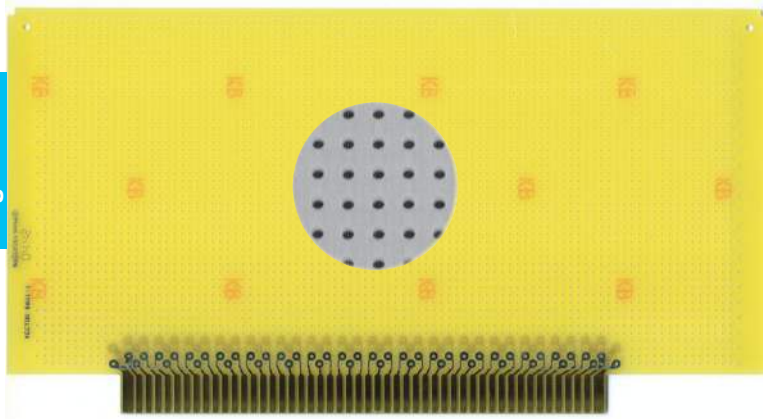
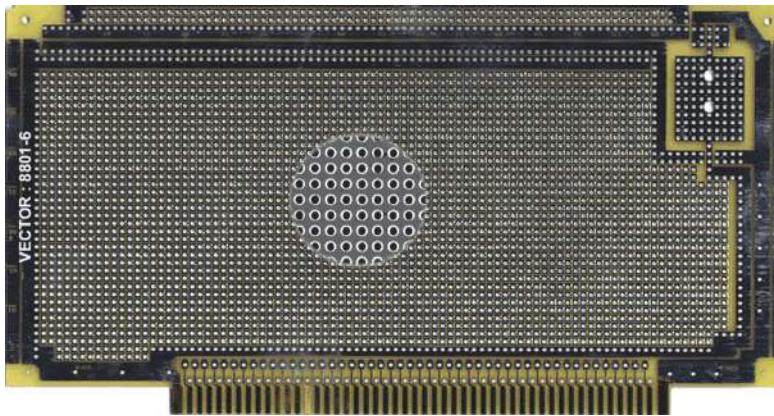


S-100 Bus



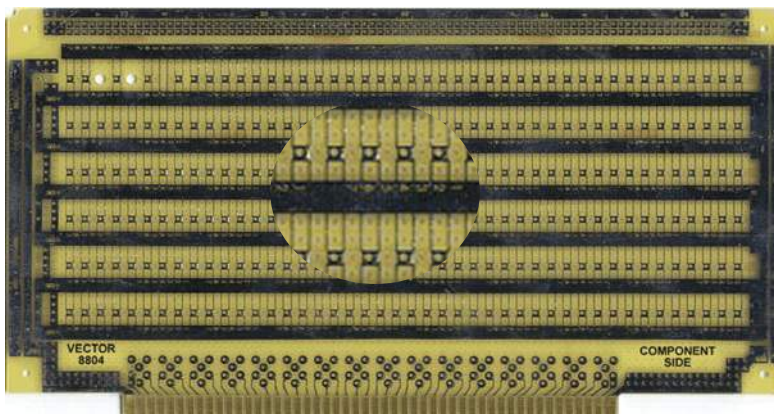
8801-1 **10.50”H x 5.3”L x .062” TH**
 0.100” grid on 0.42” diameter holes. Gold-plated edge contacts only. Bare prototyping board allows unrestricted component placement. 100 gold-plated edge contacts (50 on each side) on 0.125” centers.

16-Pin DIP Capacity:	110
WW Terminals:	T125, T126
Socket Pin:	R32
Solder Connector:	R681-3
WW Connector:	R681-2
Extender:	3690-12
Card Cage:	CCK100
Material:	FR-4



8801-6 **10.50”H x 5.3”L x .062” TH**
 0.100” grid on 0.42” diameter holes. Gold-plated edge contacts with square pad-per-hole pattern on both sides, holes plated-thru. Solder-coated copper pads. Pad area for mounting of ribbon cable I/O connector. 0.085” square pads around each hole both sides. Pin coordinate legend on board surface. Pins 1 & 51 committed to power; pins 50 & 100 committed to ground per S-100 bus specification. 100 gold-plated edge contacts (50 on each side) on 0.125” centers.

16-Pin DIP Capacity:	80
WW Terminals:	T125, T126
Socket Pin:	R32
Solder Connector:	R681-3
WW Connector:	R681-2
Extender:	3690-12
Card Cage:	CCK100
Material:	FR-4



8804 **10.50”H x 5.3”L x .062” TH**
 0.100” grid on 0.42” diameter holes. Gold-plated edge contacts with voltage/ground busses, zig-zag busses and square pads both sides. Solder-coated copper pads not plated-thru. Pad area for mounting of ribbon cable I/O connector. Pin coordinate legend on board surface. Pins 1 & 51 committed to power; pins 50 & 100 committed to ground per S-100 bus specification. 100 gold-plated edge contacts (50 on each side) on 0.125” centers.

16-Pin DIP Capacity:	70
WW Terminals:	T125, T126
Socket Pin:	R32
Solder Connector:	R656-1
WW Connector:	R656-2
Extender:	3690-16
Card Cage:	CCK13
Material:	FR-4